



FOR IMMEDIATE RELEASE

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**AEHR TEST SYSTEMS RECEIVES FOLLOW-ON ABTS™ SYSTEM
ORDER FROM MAJOR LOGIC/MIXED SIGNAL IC
MANUFACTURER**

Fremont, CA (June 6, 2012) - Aehr Test Systems (Nasdaq: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today announced receipt of a follow-on order for its advanced ABTS high-power burn-in system from a leading logic, analog and mixed signal semiconductor manufacturer.

Commenting on the follow-on order, Larry Anderson, vice president of worldwide sales of Aehr Test Systems said, “We are pleased to receive this order. The ABTS system offers high capacity and a low cost of ownership for burn-in of high-power logic devices requiring individual temperature control per device. The ABTS-L56i thermal chamber has a capacity of 56 burn-in boards and can dissipate 36 kilowatts, which is unmatched for production applications for high-power devices requiring individual device temperature control. We expect that this customer will have a need for additional ABTS systems for both production and engineering burn-in requirements, as it ramps up capacity for new higher-power ASICs and wireless and mobile processors. The ABTS is also available in smaller configurations for reliability qualifications or quality monitor applications.”

The ABTS family of products is based on a new hardware and software architecture that is designed to address not only today’s devices, but also future devices for many years to come. It is designed to test and burn-in both logic and memory devices, including resources for high pin-count devices and configurations for high-power and low-power applications. It can be configured to provide individual device temperature control for devices up to 70 watts or more and it uses N+1 redundancy technology for many key components in the system to maximize system uptime.

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability

needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, capacity needs and opportunities for Aehr Test products in package and wafer level test. Aehr Test has developed and introduced several innovative products, including the ABTS and FOXTM family of test and burn-in systems and the DiePak[®] carrier. The ABTS system is used in production and qualification testing of packaged parts for both low-power and high-power logic as well as all common types of memory devices. The FOX system is a full wafer contact test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die. For more information, please visit the Company's website at www.aehr.com.

Safe Harbor Statement

This release contains forward-looking statements that involve risks and uncertainties relating to projections regarding customer demand and acceptance of Aehr Test's products. Actual results may vary from projected results. These risks and uncertainties include, without limitation, acceptance by customers of the ABTS technology, acceptance by customers of the ABTS systems shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described. See Aehr Test's recent 10-K, 10-Q and other reports from time to time filed with the Securities and Exchange Commission for a more detailed description of the risks facing our business. The Company disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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